ZX050C-DFN3313-8 (X1-DFN3313-8) Characterization testing bringup breakout module **Product Name: Product Description:** High Speed characterization module meeting 10GHz signal bandwidth with < 0.3dB insertion loss. Each pin of the device under test, U1, is accessible via 2 dedicated SMA connectors for external stimulus as well as measurement purpose. ZX050C-DFN3313-8 is designed for ASIC (IC) characterization, functional testing of X1-DFN3313-8 packaged device. ZX50C-DFN3313-8 is designed with 50 Ω (Ohms) trace impedance using 4 layer PCB. The module includes 35 μ gold 3.0"(78mm plated SMA connectors. Ideal evaluation, bringup, and testing of any discrete component such as ESD diode, sensor, or any IC using X1-DFN3313-8 footprint package. Available SS1, SS2 optional stuffing to GND via U1 pin 3, 8. SS1, SS2 are standard 0402 SMD package footprint. User may apply any standard 0402 device as required, resistor, capacitor, bead. ... Available GND test point header pin interfacing with the module's GND plane & GND fills Simplified Block Diagram: **Application:** Bringup, Characterization, testing, development, modular design evaluations Target DUT: Designed specifically for any DFN3313-8 X1-DFN3313-8 SMD device with SMA connectors accessing all pins of the DFN3313-8 X1-DFN3313-8 Pitch: Standard DFN3313-8 X1-DFN3313-8 SMD package or equivalent D **Headers:** Ground access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height **DUT landing pads:** Surface Mount, 8 pins package - DFN3313-8 X1-DFN3313-8 or equivalent Ordering INFO: X1-DFN3313-8 DIMENTIONS (mm) Part Number La e1 ZX050C-DFN3313-8J SMA Jack Connector type (standard) 0.30 0.43 0.700 max ZX050C-DFN3313-8P SMA Plug connector type **Typical** 0.25 3.30 1.30 0.50 1.250 0.38 0.650 0.20 0.30 0.570 min NOTE: ZX050C-DFN3313-8 is shipped without DUT. All SMA 7 connectors are installed. REFERENCES **OUTLINE Version** IEC JEDEC **JEITA** SS1, SS2 are standard 0402 SMD package footprint – The pads are shorted making it 0Ω as default. C1 is standard 0402 SMD package PLUG SMA: Pad Layout Impedance: 50Ω -65°C +165°C Temp Range: Vibration: MIL-STD-202, Method 213 Frequency Range: DC - 12GHz ALL ZEBAX products are RoHS compliant and Lead Free unless otherwise indicated. Working Voltage: 335V max Withstand Voltage: 1000V rms Center Contact: $\leq 3m\Omega$ Outer Contact: $\leq 2m\Omega$ ZEBAX TECHNOLOGIES Insulation resistance: ≥5000MΩ SANTA CRUZ, CA U.S.A (831) 2 2 2 - 0717 VSWR Straight: $\leq 1.15 (0.8-2.5G)$ WWW.ZEBAX.COM ASSEMBLY DRAWING SPECIFIED DIMENSIONS ARE INCHES (MM). ITEM: ZX050C-DFN3313-8 DESCRIPTION: X1-DFN3313-8 DFN3313-8 characterization testing ALL ZEBAX TECHNOLOGIES DESIGN SPECIFICATIONS, DRAWINGS, PUBLICATIONS, AND OTHER DOCUMENTS (TOGETHER AND SEPARATELY, "MATERIALS") ARE BEING PROVIDED "AS IS." ZEBAX MAKES NO WARRANTIES, EXPRESSED, bringup breakout adapter SMA IMPLIED, STATUTORY, OR OTHERWISE WITH RESPECT TO THE MATERIALS, AND EXPRESSLY DISCLAIMS ALL IMPLIED WARRANTIES OF NO INFRINGEMENT, MERCHATABILITY, AND FITNESS FOR A PARTICULAR PURPOSE. Information furnished is believed to be accurate and reliable. However, Zebax Technologies assumes no responsibility for the consequences of use of such information or for any infringement of patents or other rights of third parties that may result from its use. DRAWN: REVISSION: 1.0 Specifications mentioned in this publication are subject to change without notice. This publication replaces all other information previously supplied. Zebax Technologies products are not authorized as in life support devices or systems

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